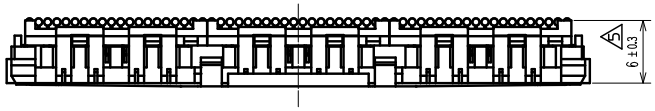
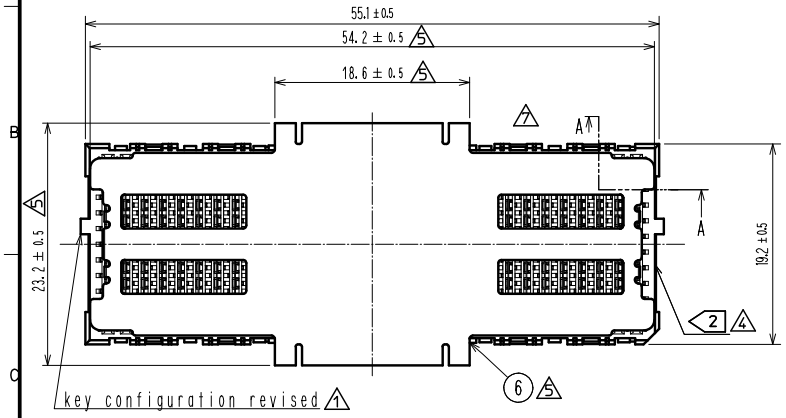
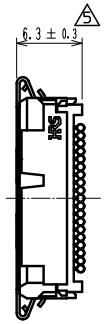
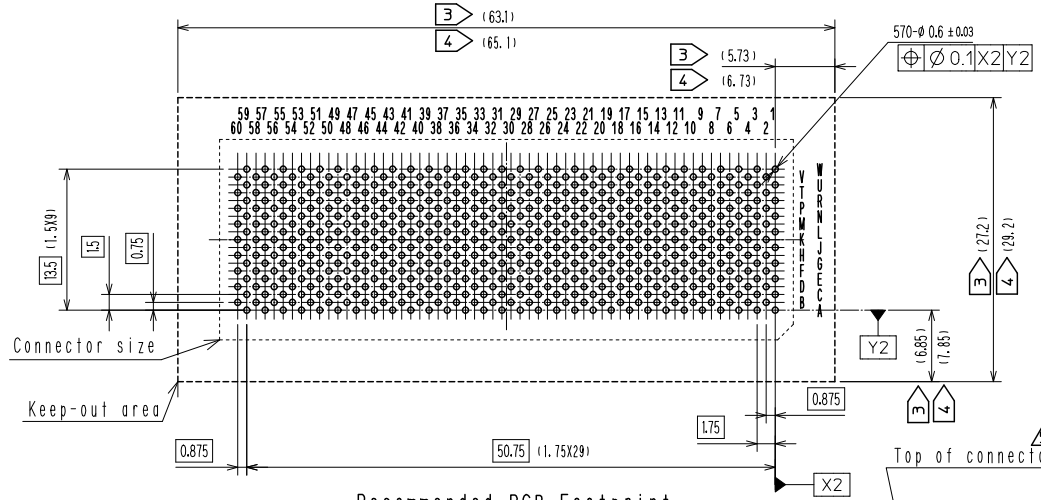
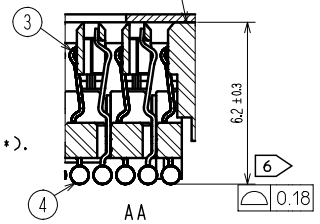


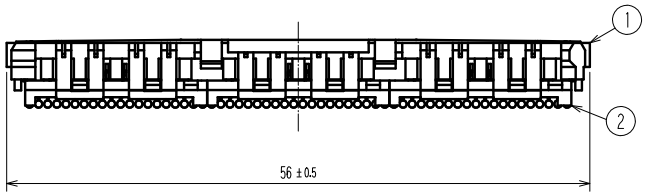


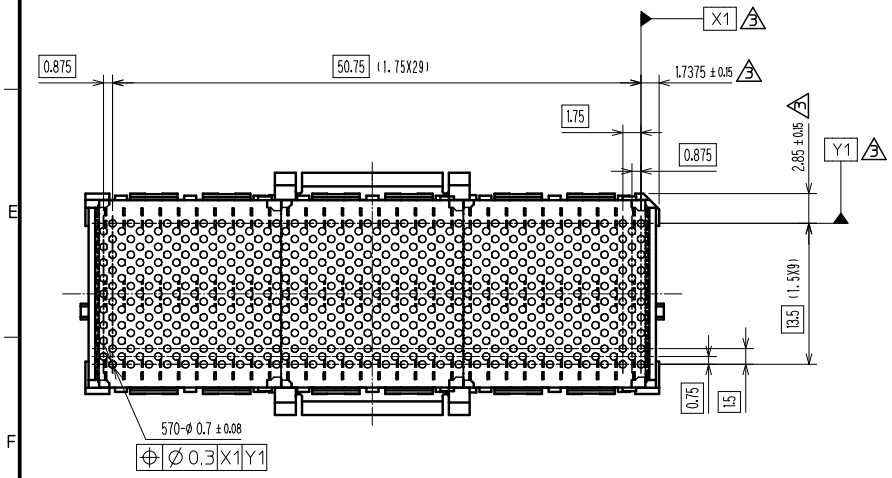




Recommended PCB Footprint
(Connector Side)







NOTE

1 IT3D receptacle to be mated and unmated with IT3-300P-**H(**).

2 Lot no. is marked on top of the connector.

3 Minimum clearance for all devices.

4 Minimum clearance for sensitive devices.

5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".

6 Maximum coplanarity of the ball field is 0.18mm.

7 Please remove the pick up cap (part No.6) from the IT3 connector after reflow soldering.

8 The removed pick up cap (part No.6) should not be reused.

9 Standard package of 48pcs are packaged in a carton box.

10 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.

11 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
3	Copper alloy	Contact area : Nickel(1.5μm) + Gold(0.76μm) Other area : Nickel(1.5μm)	6	SUS 5	PICK UP CAP 5
2	LCP	BLACK . UL94V-0	5	HIPS	TRAY. BLACK
1	LCP	BLACK . UL94V-0	4	TIN-LEAD	Sn(63)-Pb(37)

UNITS	SCALE	REV	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	1	1	REVISED CAP SHAPE	TS. KIKUCHI	TS. MATSUO	09. 10. 15

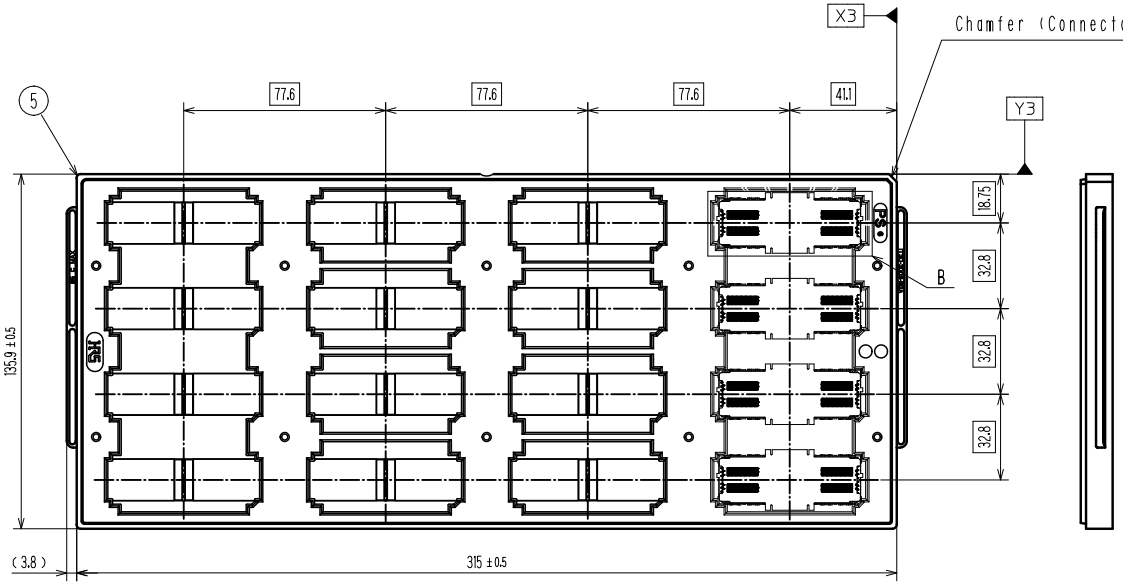
HIROSE ELECTRIC CO., LTD.

APPROVED : T. Matsuo	07/26/2007	DRAWING NO. EDC3-157108-02
CHECKED : T. Matsuo	07/26/2007	PART NO. IT3D-300S-BGA(57)
DESIGNED : T. Takada	07/26/2007	
DRAWN : T. Takada	07/26/2007	CODE NO. CL636-0007-9-57

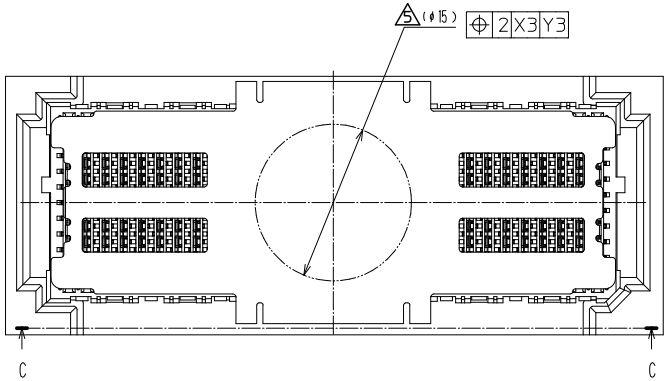
1/2

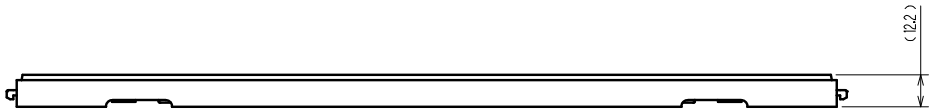
FORM NO.229-1

Tray Package(1:2) 5

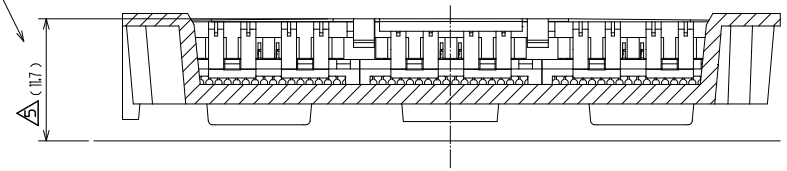


Area for vacuum nozzle





Dimension from bottom of tray to top of connector 2



CC

HRS	DRAWING NO.	EDC3-157108-02
	PART NO.	IT3D-300S-BGA(57)
	CODE NO.	CL636-0007-9-57

1 2

FORM NO.229-2